

### QM6001D-VB Datasheet

## P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	<b>R<sub>DS(on)</sub> (</b> Ω <b>)</b>	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ)		
- 60	0.061 at V <sub>GS</sub> = - 10 V	- 30	10		
- 60	0.072 at V <sub>GS</sub> = - 4.5 V	- 25	10		

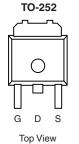
#### FEATURES

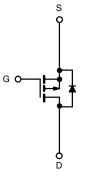
- Trench Power MOSFET
- 100 % UIS Tested

#### **APPLICATIONS**

Load Switch







P-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Gate-Source Voltage	V <sub>GS</sub>	± 20	V		
Continuous Drain Current (T <sub>.1</sub> = 175 °C)	T <sub>C</sub> = 25 °C	L_	- 30		
Continuous Drain Current $(1) = 175$ C)	T <sub>C</sub> = 100 °C	I <sub>D</sub>	- 25		
Pulsed Drain Current	I <sub>DM</sub>	- 30	А		
Continuing Source Current (Diode Conduction)	۱ <sub>S</sub>	- 20			
Avalanche Current	I <sub>AS</sub>	- 20			
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	7.2	mJ	
Maximum Dawar Dissinction	T <sub>C</sub> = 25 °C	Pn	34 <sup>a</sup>	w	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C		4 <sup>b</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
harding to Arching	$t \le 10 \text{ sec}$	D	20 25		
Junction-to-Ambient <sup>D</sup>	Steady State	R <sub>thJA</sub>	62	75	°C/W
Junction-to-Case	•	R <sub>thJC</sub>	5	6	

Notes:

a. See SOA curve for voltage derating.

b. Surface Mounted on 1" x 1" FR-4 boad.

<b>SPECIFICATIONS</b> $T_J = 25$	°C, unless	otherwise noted					
Parameter	Symbol	Test Conditions	Min	Typ <sup>a</sup>	Мах	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 V, I_D = -250 \mu A$	- 60			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = -250 \ \mu A$	- 1.0	- 2.0	- 3.0	v	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS}$ = - 60 V, $V_{GS}$ = 0 V, $T_{J}$ = 125 °C			- 50	μΑ	
		$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 \text{ °C}$			- 150		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	- 10			А	
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 5 A		0.061			
	r	$V_{GS}$ = - 10 V, I <sub>D</sub> = - 5 A, T <sub>J</sub> = 125 °C		0.100			
Drain-Source On-State Resistance <sup>b</sup>	r <sub>DS(on)</sub>	$V_{GS}$ = - 10 V, I <sub>D</sub> = - 5 A, T <sub>J</sub> = 175 °C		0.150		Ω	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 2 A		0.072			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 5 A		8		S	
Dynamic	•	•		•			
Input Capacitance	C <sub>iss</sub>			1000		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ = - 25 V, $V_{GS}$ = 0 V, f = 1 MHz		120			
Reverse Transfer Capacitance	C <sub>rss</sub>			100			
Total Gate Charge	Qg			10			
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = -30$ V, $V_{GS} = -10$ V, $I_{D} = -8.4$ A		2.1		nC	
Gate-Drain Charge	Q <sub>gd</sub>			3.2		1	
Gate Resistance	R <sub>g</sub>	f = 1 MHz		8.0		Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			6			
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = - 30 V, $R_{L}$ = 3.57 $\Omega$		15			
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$\text{I}_{\text{D}}\cong$ - 8.4 A, $\text{V}_{\text{GEN}}$ = - 10 V, $\text{R}_{\text{G}}$ = 2.5 $\Omega$		16		ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			8			
Source-Drain Diode Ratings and Cha	aracteristics	(T <sub>C</sub> = 25 °C) <sup>b</sup>					
Pulsed Current	I <sub>SM</sub>				- 30	А	
Forward Voltage <sup>b</sup>	V <sub>SD</sub>	$I_{F} = -2 \text{ A}, V_{GS} = 0 \text{ V}$		- 0.9	- 1.3	V	
Reverse Recovery Time	t <sub>rr</sub>	L = 8.4  di/dt = 100.4/ma		50		ns	
Reverse Recovery Time	Q <sub>rr</sub>	I <sub>F</sub> = - 8 A, di/dt = 100 A/μs		80		nC	

Notes:

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

c. Independent of operating temperature.

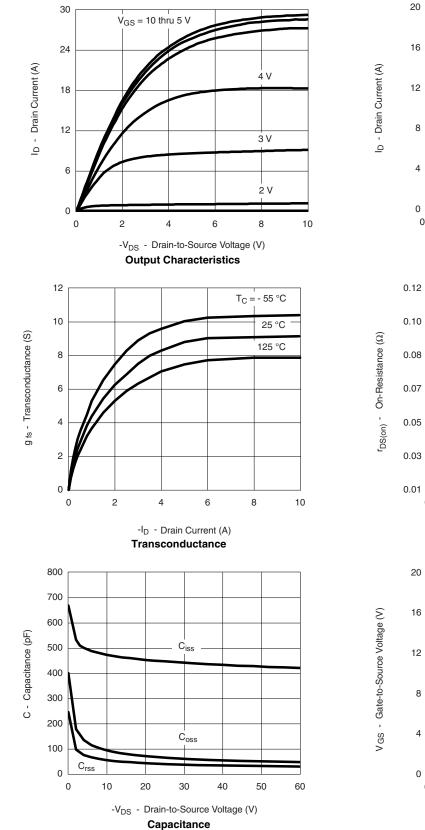
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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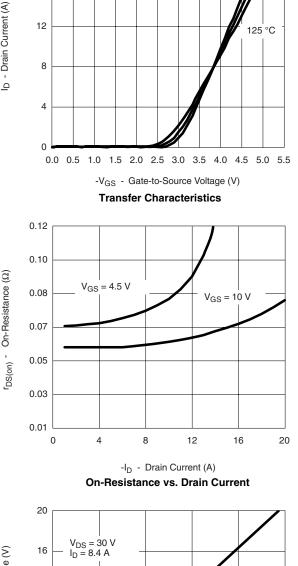


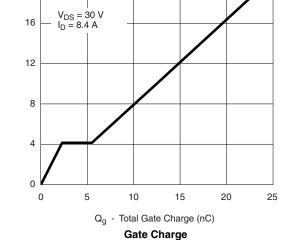
T<sub>C</sub> = - 55 °C

1 25 °C

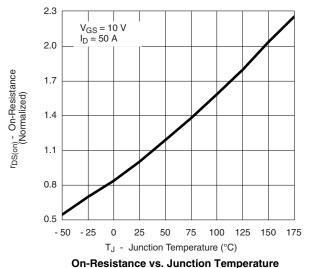


#### TYPICAL CHARACTERISTICS 25 °C unless noted

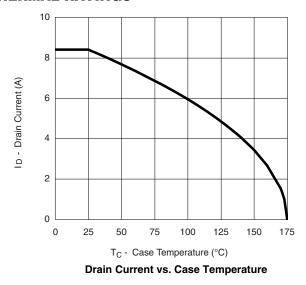


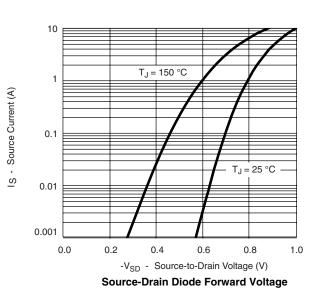


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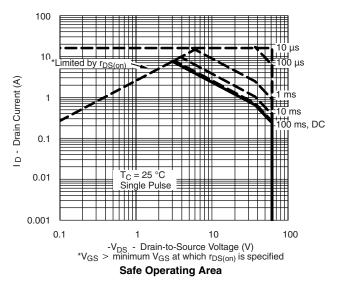






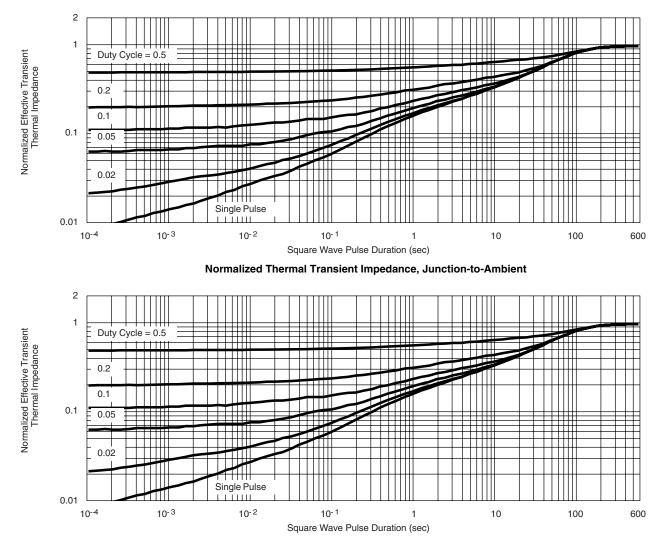
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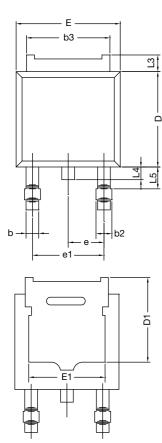
#### THERMAL RATINGS

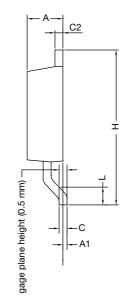


Normalized Thermal Transient Impedance, Junction-to-Case



## **TO-252AA CASE OUTLINE**





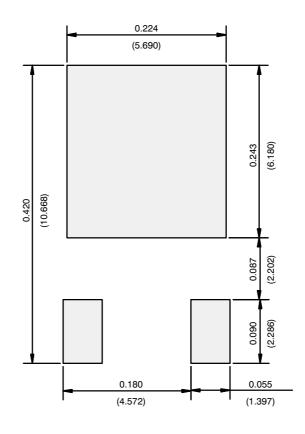
	MILLIN	INC	CHES			
DIM.	MIN.	MAX.	MIN.	MAX.		
А	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	5.21	-	0.205	-		
Е	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28 BSC		0.090 BSC			
e1	4.56	BSC	0.180	0.180 BSC		
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.14	1.52	0.045	0.060		
ECN: X12- DWG: 5347	0247-Rev. M, 7	24-Dec-12				

Note

• Dimension L3 is for reference only.



#### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



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